

HSF

Specification

- 1.Current Rating:1.5AMP
- 2.Contact Resistance:30mΩ max
- 3.Insulation Resistance:1000MΩ min
- 4.Dielectric Withstanding Voltage:500V R.M.S
- 5.Temperature Rating:-40℃ to +85℃

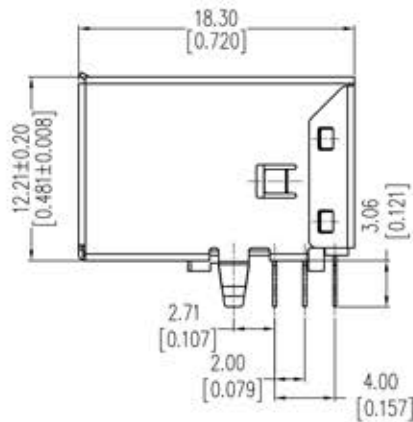
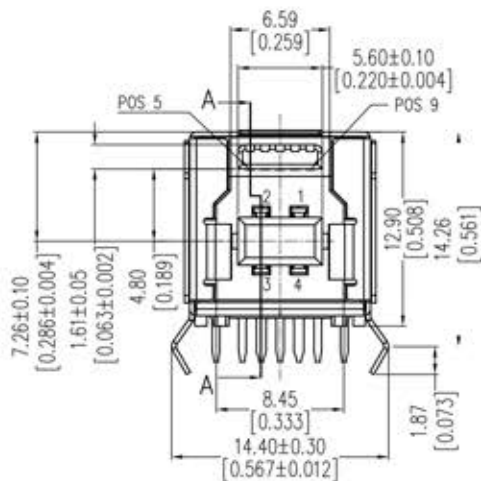
Mechanical Characteristics:

- 6.Mating Force:3.57kg.min
- 7.Mating Force:1.02kg.min
- 8.Durability: Mandatory:5000 Cycles

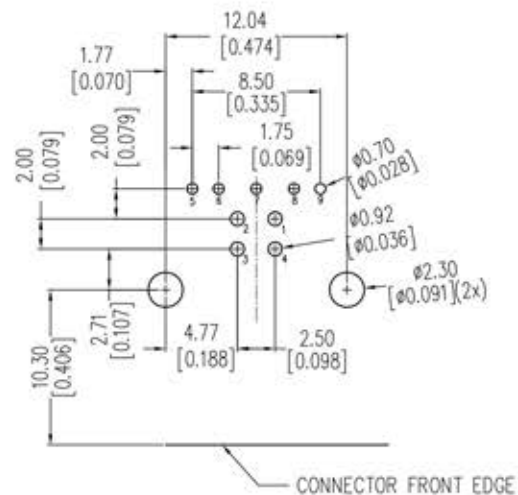
Contact: Copper(T=0.20mm)

Insulator: LCP+30%GF(UL94V-0)

Shell: Brass(T=0.30mm)



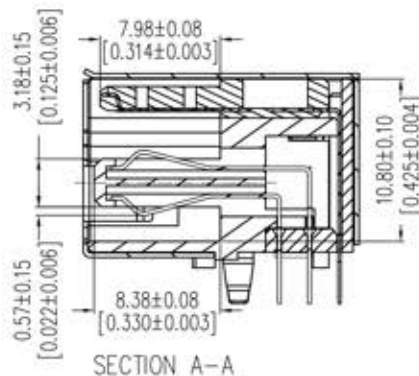
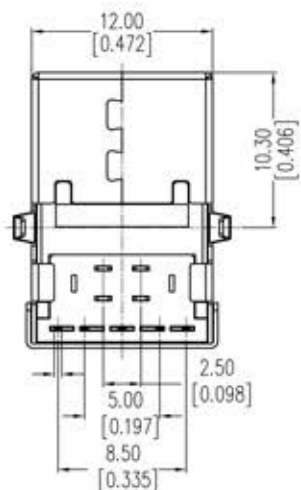
Recommended P.C.B Layout(Top Side)
 (PCB BOARD TOLERANCE ± 0.05)



Ordering Information

6112-09 BFR D XX UN A I

- Contact Plating:
 S0=Gold Flash/Tin
 S1=3u"Gold/Tin
 S2=5u"Gold/Tin
 S3=10u"Gold/Tin
 S4=15u"Gold/Tin
 S5=30u"Gold/Tin
- Plating:
 B=Black
 W=White
 U=Blue
 R=Red
- Packing:
 A=Tray
- Series No.



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
A0	2012/06/30	NEW		X.X ± 0.40	JYHuang	2012/06/30	UNIT	mm	6112-09BFRDXXXNA1
				X.XX ± 0.25	CHECK	DATE	SIZE	A4	TITLE:
				X.XXX ± 0.15	APPROVE	DATE	SHEET	1/1	USB3.0B-TYPE FEMALE 90°
				Angle ± 3'			PROJ.	Customer NO.	壳高12.21, H=12.90, 1.87长弯脚DIP
				DIM TOL					